



Material Content Data Sheet



Sales Product Name		BGM 15LA12 E6327		Issued		20. July 2018		
MA#		MA001333284						
Package		PG-ATSLP-12-1		Weight*		3.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.311	8.48	8.48	84793	84793
bumps	non noble metal	copper	7440-50-8	0.022	0.59	0.59	5882	5882
encapsulation	organic material	carbon black	1333-86-4	0.012	0.34		3359	
	plastics	epoxy resin	-	0.357	9.74		97409	
	inorganic material	silicondioxide	60676-86-0	2.093	57.09	67.17	571016	671784
leadfinish	noble metal	gold	7440-57-5	0.024	0.66		6630	
	non noble metal	nickel	7440-02-0	0.028	0.76	1.42	7561	14191
substrate	organic material	carbon black	1333-86-4	0.001	0.02		249	
	plastics	epoxy resin	-	0.036	0.97		9701	
	inorganic material	silicondioxide	60676-86-0	0.267	7.30		72964	
	non noble metal	copper	7440-50-8	0.444	12.12	20.41	121199	204113
ubm	non noble metal	copper	7440-50-8	0.000	0.01		89	
	non noble metal	titanium	7440-32-6	0.000	0.00		32	
	non noble metal	tungsten	7440-33-7	0.000	0.00	0.01	16	137
solder	noble metal	silver	7440-22-4	0.000	0.01		74	
	non noble metal	tin	7440-31-5	0.012	0.32	0.33	3161	3235
solder resists	inorganic material	bariumsulfate	7727-43-7	0.013	0.34		3411	
	inorganic material	silicondioxide	60676-86-0	0.012	0.34		3371	
	plastics	acrylic resin	-	0.033	0.91	1.59	9083	15865
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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